

AB817B-B

Photocoupler

DESCRIPTIONS

- The AB817B-B (1-channel) is optically coupled isolators containing a GaAs Light Emitting Diode and an NPN silicon phototransistor
- The lead pitch is 2.54mm

FEATURES

- Lead forming (gull wing) type, for surface mounting
- · High isolation voltage between input and output (Viso=5000 Vrms)
- Compact dual-in-line package AB817B-B:1-channel type
- Package: 1000 pcs / reel
- Moisture sensitivity level: 4
- · RoHS compliant

APPLICATIONS

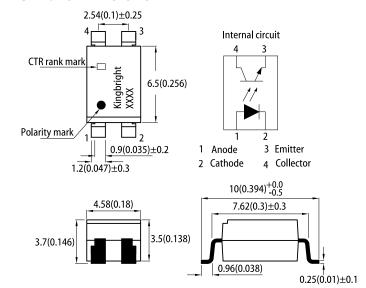
- · Computer terminals
- Registers, copiers, automatic vending machines
- System appliances, measuring instruments
- Programmable logic controller
- · Signal transmission between circuits of different potentials and impedances

NOTES ON HANDLING

Cautions regarding electrical noise

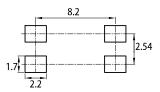
Please ensure the power supply is stable at all times. Even if the designed operating voltage is within specification limits, sudden voltage spikes at startup may damage the component.

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm: tolerance: ± 0.15)



- 1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.5(0.02") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

ELECTRICAL / OPTICAL CHARACTERISTICS at T₄=25°C

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Parameter		Symbol	Min.	Тур.	Max.	Units	Test Conditions	
	Forward voltage		V _F	-	1.2	1.4	V	I _F =20mA
Input	Peak forward voltage		V _{FM}	-	-	3.0	V	I _{FM} =0.5A
	Reverse current		I _R	-	-	10	μA	V _R =4V
Output	Collector dark current		I _{CEO}	-	-	10 ⁻⁷	Α	I _F =0mA,V _{CE} =20V
Transfer characteristics	Current transfer ratio [1]		CTR	130	-	260	%	I _F =5mA,V _{CE} =5V
	Collector-emitter saturation voltage		V _{CE(sat)}	-	0.1	0.2	V	I _F =20mA,I _C =1mA
	Cut-off frequency		f _c	-	80	-	kHz	V_{CE} =5V, I_{C} =2mA R_{L} =100 Ω ,-3dB
	Response time	Rise time	t _r	-	4	18	μs	V_{CE} =2V, I_{C} =2mA R_{L} =100 Ω
		Fall time	t _f	-	3	18	μs	

^{1.}Classification table of current transfer ratio is shown below.

 $CTR = \frac{I_C}{I_C} X 100\%$

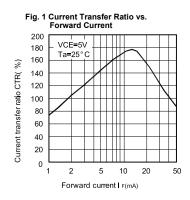
^{2.} Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

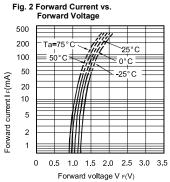


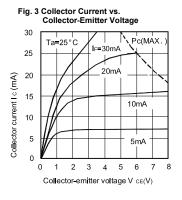
ABSOLUTE MAXIMUM RATINGS at T_A=25°C

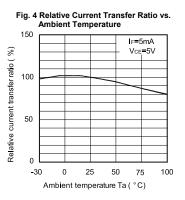
Parameter		Symbol	Rating	Unit
Input	Forward current	l _F	50	mA
	Reverse voltage	V_{R}	6	V
	Power dissipation	P_D	70	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	Ic	50	mA
	Collector power dissipation	Pc	150	mW
Total power dissipation		P _{tot}	200	mW
Isolation voltage [1]		$V_{\rm iso}$	5000	Vrms
Operating temperature		T_{opr}	-30~+100	°C
Storage temperature		T_{stg}	-55~+125	°C

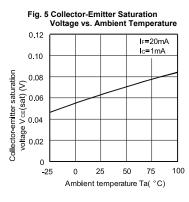
TECHNICAL DATA

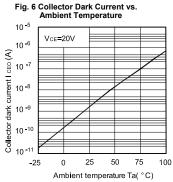


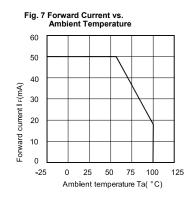


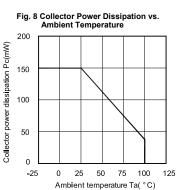










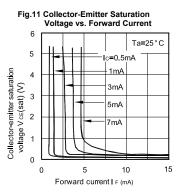


^{1.40} to 60% RH,AC for 1 minute.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

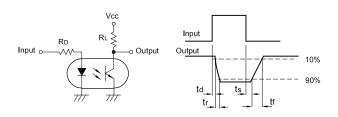


Fig. 9 Response Time vs. Load Resistance 500 200 Ic=2mA 100 50 Response time (µs) 10 5 0.5 0.2 Load resistance R $_{\perp}$ (K Ω)

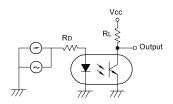
Fig.10 Frequency Response VcE=2V 0 Voltage gain Av (dB) -10 -20 5 10 20 50 Frequency f (kHz)



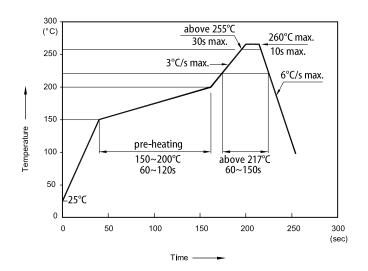
Test Circuit for Response Time



Test Circuit for Frequency Response



REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



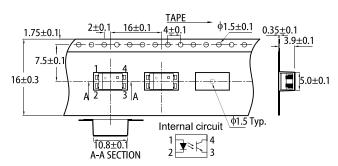
Notes:

- 1. Don't cause stress to the LEDs while it is exposed to high temperature.

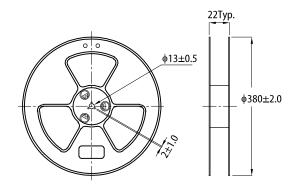
 2. The maximum number of reflow soldering passes is 2 times.

 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units:mm)

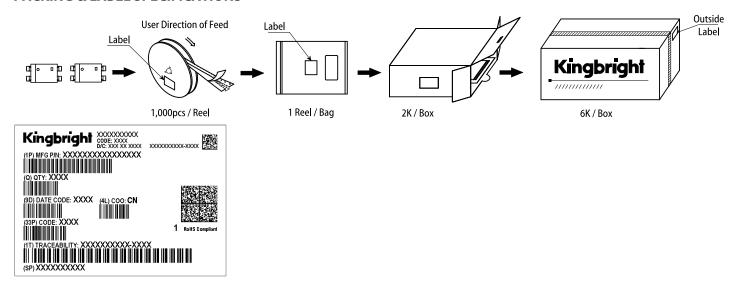


REEL DIMENSION (units: mm)





PACKING & LABEL SPECIFICATIONS



RESTRICTIONS ON PRODUCT USE

- The information in this document represents typical usage and is provided for technical reference.

 The information in this document is subject to change without notice. Please refer to the latest version of this document for the most updated information.

 Please ensure this product is used in accordance with the electrical and environmental specifications and tolerances listed in this document. If the usage exceeds the specification
- range, Kingbright will not be responsible for any subsequent issues.

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